## How to Place Leakage and Wiring Inductances in the High Frequency Circuit Model

by Lloyd Dixon

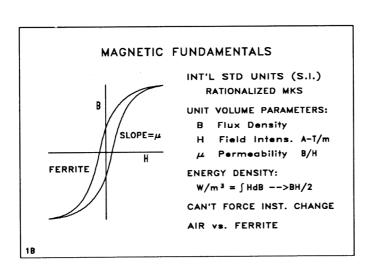
# How to Put Leakage and Wiring Inductances in the High Frequency Circuit Model

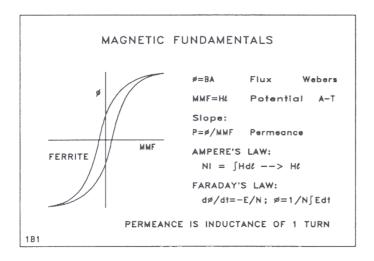
### Lloyd H. Dixon, Jr.

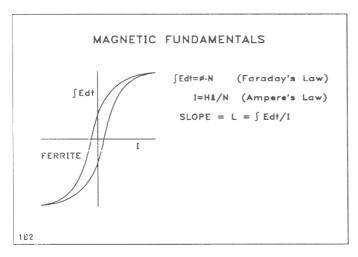
#### **OBJECTIVES**

- DEFINE THE ELECTRICAL CIRCUIT EQUIVALENTS
   OF MAGNETIC DEVICE STRUCTURES TO ENABLE
   IMPROVED ANALYSIS OF CIRCUIT PERFORMANCE.
- DEFINE THE MAGNITUDE AND CIRCUIT LOCATION OF RELEVANT PARASITIC MAGNETIC ELEMENTS TO ENABLE PREDICTION OF PERFORMANCE EFFECTS.
- MANIPULATE PARASITIC ELEMENTS TO OBTAIN IMPROVED OR ENHANCED CIRCUIT PERFORMANCE.
- 4. ENCOURAGE THE CIRCUIT DESIGNER TO BE MORE INVOLVED WITH MAGNETIC DEVICE DESIGN.

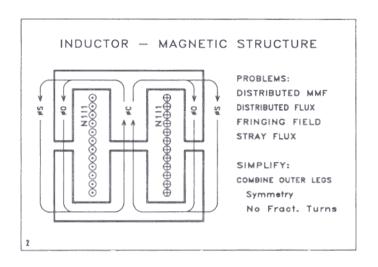
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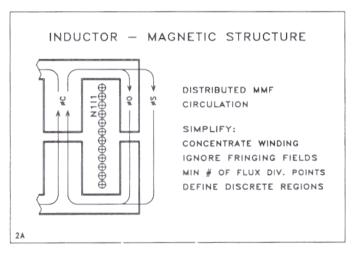


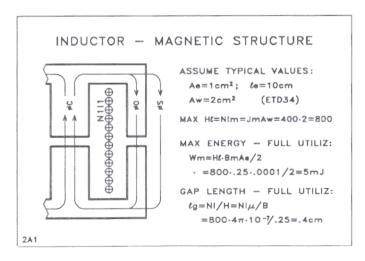


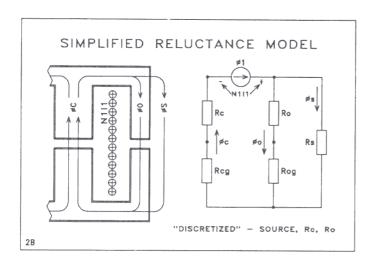


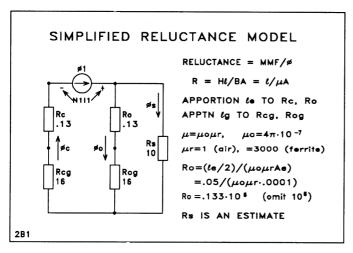
	SI		
_		cgs	CGS to SI
B	Tesla	Gauss	10 -4
Н	A-T/m	Oersted	$1000/4\pi$
) μο	4π-10 <sup>-7</sup>	1	4π·10 <sup>-7</sup>
			1
A	m	cm	10 -4
1	•	cm	10 -2
#	Weber	Maxwell	10 →
F, MMF	A-T	Gilbert	10/4π
R			$10^{9}/4\pi$
P			4π-10-
Ł	Henry	(Henry)	1
w	Joule	Erg	10 <sup>-7</sup>
	) μο  A  I  #  F, MMF  R  P  L	) μο 4π-10 <sup>-7</sup> A m  I	) μο 4π-10 <sup>-7</sup> 1  A m cm I s cm # Weber Maxwell F, MMF A-T Gilbert R P L Henry (Henry)

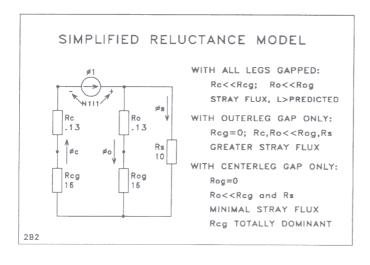


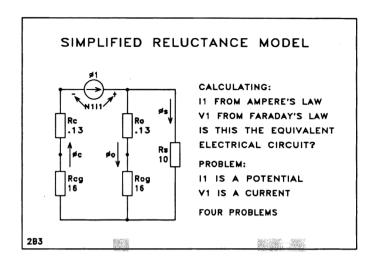




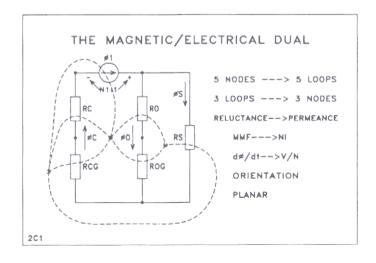


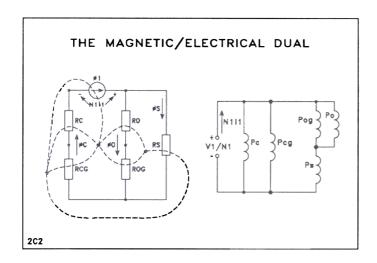


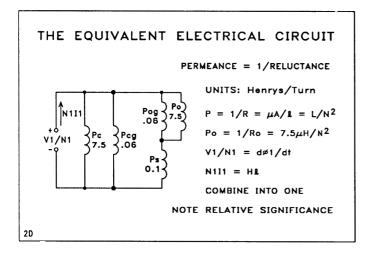


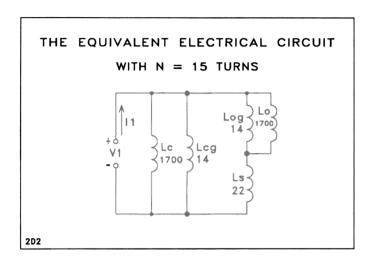


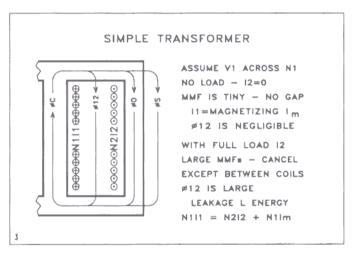
#### THE EQUIVALENT ELECTRICAL CIRCUIT IS A DUAL OF THE MAGNETIC CIRCUIT (ELECTRICAL DUALS ARE NOT EQUIVALENT: CUK VS FLYBACK) MAGNETIC - ELECTRICAL DUALITY: NODES MESHES (LOOPS) MMF AMP-TURNS dø/dt VOLTS/TURN RELUCTANCE PERMEANCE SHORT **OPEN** SERIES ADDN. PAR. ADDN. ORIENTATION: ROTATE IN SAME DIRECTION CIRCUITS MUST BE PLANAR 2C

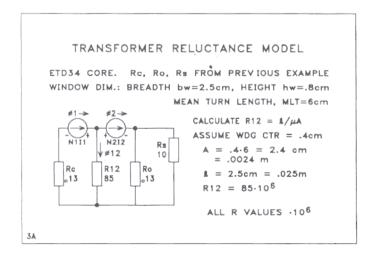


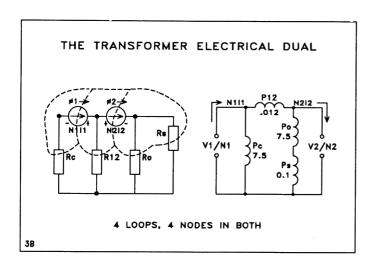


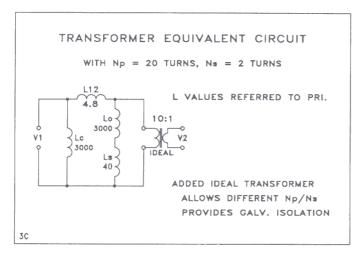


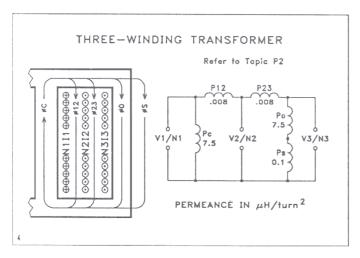


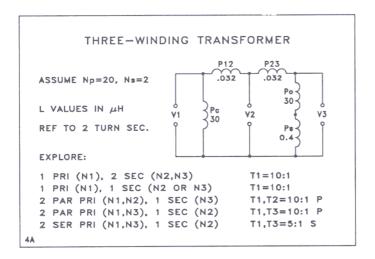


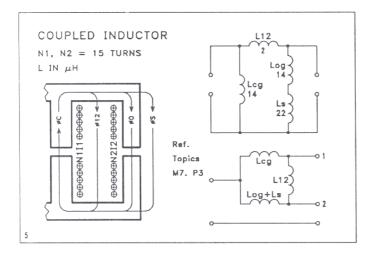


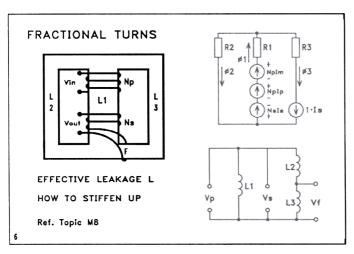












#### REFERENCES

- 1. CHERRY, E.C., "The Duality Between Electric and Magnetic Circuits and the Formation of Transformer Equivalent Circuits," Proc. Phys. Soc. (Britain), 62B, pp 101—111, Feb. 1949
- 2. Severns and Bloom, "Modern DC—to—DC Switchmode Power Converter Circuits," Van Nostrand Reinhold Co., Inc., New York, 1985.
- 3. Dauhaire and Middlebrook, "Modelling and Estimation of Leakage Phenomena in Magnetic Circuits," IEEE Power Electronics Specialists Conference, 1986 Record, pp. 213—226.

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